PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Kyoungmin PARK	05/02/2012
Sungjin SUH	05/02/2012

RECEIVING PARTY DATA

Name:	Pantech Co., Ltd.
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City:	Seoul
State/Country:	KOREA, REPUBLIC OF
Postal Code:	121-270

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13505637

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ATTORNEY DOCKET NUMBER:	P4820US00
NAME OF SUBMITTER:	Hae-Chan Park

Total Attachments: 2
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OP $40.00 13505637

Attorney's Docket No.: P4820US00

ASSIGNMENT

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in

☒ an application for United States Letters Patent entitled **CHANNEL INFORMATION FEEDBACK DEVICE AND METHOD THEREOF, AND MODE SWITCHING METHOD, COMMUNICATION TERMINAL DEVICE, AND BASE STATION SYSTEM USING SAME** ("Application");

☐ upon which United States Letters Patent, Patent Number ______________, has issued ("Patent");

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

PANTECH CO., LTD.
Pantech Bldg. R&D Center, I-2, DMC
Sangam-dong, Mapo-gu
121-270 Seoul
Republic of Korea

PANTECH CO., LTD. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Assignor has hereunto set hand and seal.

First Inventor's Name: Kyoungmin PARK

Address:
Pantech Bldg. R&D Center, I-2, DMC
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Republic of Korea

First Inventor's Signature: ______________________

Date: May 2, 2012

Second Inventor's Name: Sungjin SUH

Address:
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Sangam-dong, Mapo-gu
121-270 Seoul
Republic of Korea

Second Inventor's Signature: ______________________

Date: May 2, 2012